

# PJQ4460AP

## 60V N-Channel Enhancement Mode MOSFET

Voltage

60 V

Current

11 A

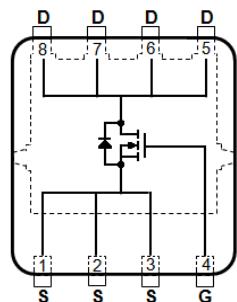
### Features

- $R_{DS(ON)}$ ,  $V_{GS} @ 10V$ ,  $I_D @ 6A < 72m\Omega$
- $R_{DS(ON)}$ ,  $V_{GS} @ 4.5V$ ,  $I_D @ 3A < 88m\Omega$
- Advanced Trench Process Technology
- High density cell design for ultra low on-resistance
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

### Mechanical Data

- Case : DFN3333-8L Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.03 grams

DFN3333-8L



### Maximum Ratings and Thermal Characteristics ( $T_A=25^\circ C$ unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS
Drain-Source Voltage		$V_{DS}$	60	V
		$V_{GS}$	$\pm 20$	
Continuous Drain Current( <sup>Note 4</sup> )	$T_C=25^\circ C$	$I_D$	11	A
	$T_C=100^\circ C$		7	
Pulsed Drain Current( <sup>Note 1</sup> )	$T_C=25^\circ C$	$I_{DM}$	44	
Power Dissipation	$T_C=25^\circ C$	$P_D$	20	W
	$T_C=100^\circ C$		8	
Continuous Drain Current( <sup>Note 4</sup> )	$T_A=25^\circ C$	$I_D$	3.7	A
	$T_A=70^\circ C$		2.9	
Power Dissipation	$T_A=25^\circ C$	$P_D$	2	W
	$T_A=70^\circ C$		1.3	
Single Pulse Avalanche Energy( <sup>Note 6</sup> )		$E_{AS}$	25	mJ
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~150	°C
Typical Thermal Resistance( <sup>Note 4,5</sup> )	Junction to Case	$R_{\theta JC}$	6.3	°C/W
	Junction to Ambient	$R_{\theta JA}$	62.5	

- Limited only By Maximum Junction Temperature

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## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
<b>Static</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	60	-	-	V
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	1	1.8	2.5	
Drain-Source On-State Resistance	$\text{R}_{\text{DS}(\text{on})}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=6\text{A}$	-	53	72	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}, \text{I}_D=3\text{A}$	-	61	88	
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=60\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm 20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
<b>Dynamic</b> <sup>(Note 7)</sup>						
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=48\text{V}, \text{I}_D=6\text{A}, \text{V}_{\text{GS}}=10\text{V}$ <sup>(Note 1,2)</sup>	-	9.3	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	2.2	-	
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	1.9	-	
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=15\text{V}, \text{V}_{\text{GS}}=0\text{V}, f=1\text{MHZ}$	-	509	-	pF
Output Capacitance	$\text{C}_{\text{oss}}$		-	47	-	
Reverse Transfer Capacitance	$\text{Crss}$		-	23	-	
Turn-On Delay Time	$\text{t}_{\text{d}(\text{on})}$	$\text{V}_{\text{DD}}=30\text{V}, \text{I}_D=1\text{A}, \text{V}_{\text{GS}}=10\text{V}, \text{R}_G=3.3\Omega$ <sup>(Note 1,2)</sup>	-	3.2	-	ns
Turn-On Rise Time	$\text{t}_r$		-	9.7	-	
Turn-Off Delay Time	$\text{t}_{\text{d}(\text{off})}$		-	18.5	-	
Turn-Off Fall Time	$\text{t}_f$		-	6.4	-	
<b>Drain-Source Diode</b>						
Maximum Continuous Drain-Source Diode Forward Current	$\text{I}_s$	---	-	-	11	A
Reverse Recovery Time	$\text{V}_{\text{SD}}$	$\text{I}_s=1\text{A}, \text{V}_{\text{GS}}=0\text{V}$	-	0.75	1	V

### NOTES :

1. Pulse width $\leq 300\mu\text{s}$ , Duty cycle $\leq 2\%$ .
2. Essentially independent of operating temperature typical characteristics.
3. Repetitive rating, pulse width limited by junction temperature  $\text{T}_{\text{J}(\text{MAX})}=150^\circ\text{C}$ . Ratings are based on low frequency and duty cycles to keep initial  $\text{T}_j=25^\circ\text{C}$ .
4. The maximum current rating is package limited.
5.  $\text{R}_{\text{QJA}}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
6. The test condition is  $L=1\text{mH}, \text{I}_{\text{AS}}=7\text{A}, \text{V}_{\text{DD}}=25\text{V}, \text{V}_{\text{GS}}=10\text{V}$ , Starting  $\text{T}_j=25^\circ\text{C}$ .
7. Guaranteed by design, not subject to production testing.

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## TYPICAL CHARACTERISTIC CURVES

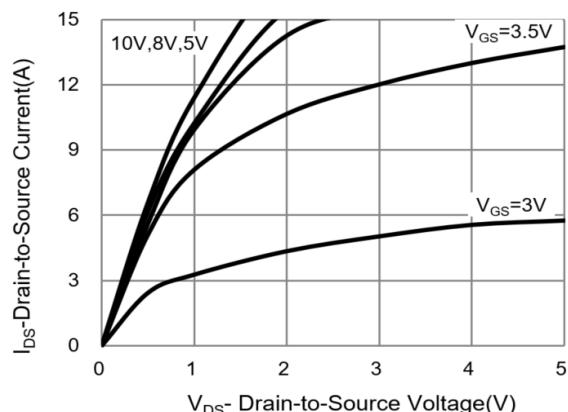


Fig.1 On-Region Characteristics

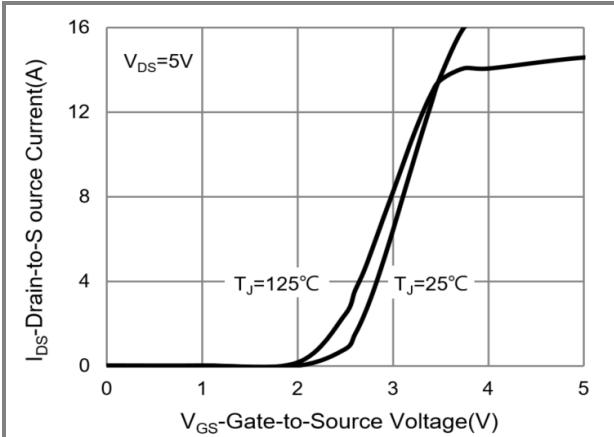


Fig.2 Transfer Characteristics

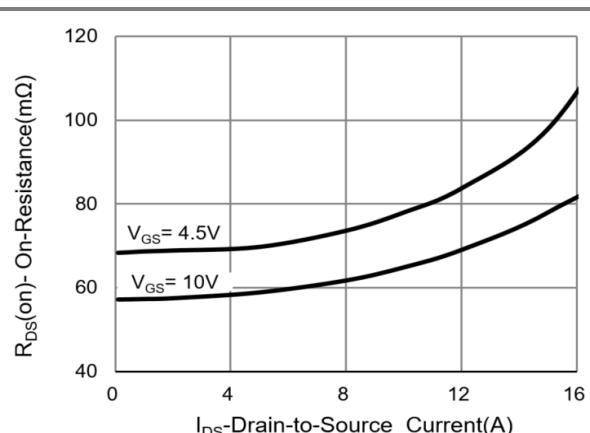


Fig.3 On-Resistance vs. Drain Current

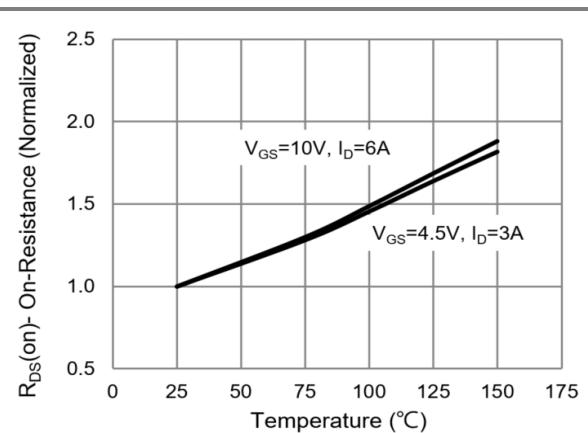


Fig.4 On-Resistance vs. Junction temperature

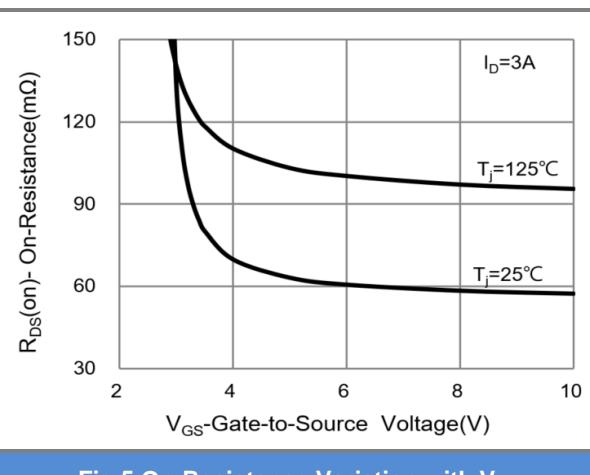


Fig.5 On-Resistance Variation with V<sub>G</sub>

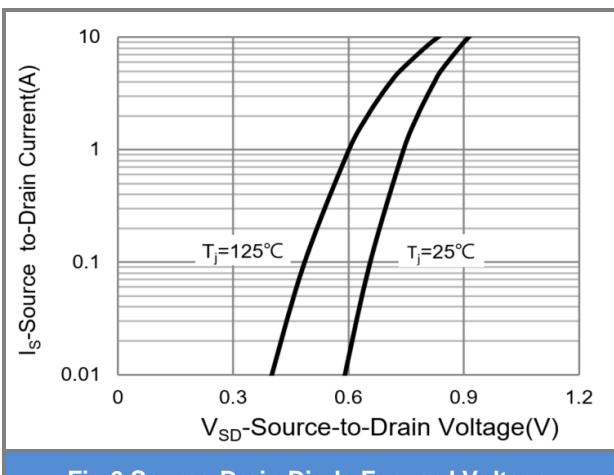


Fig.6 Source-Drain Diode Forward Voltage

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## TYPICAL CHARACTERISTIC CURVES

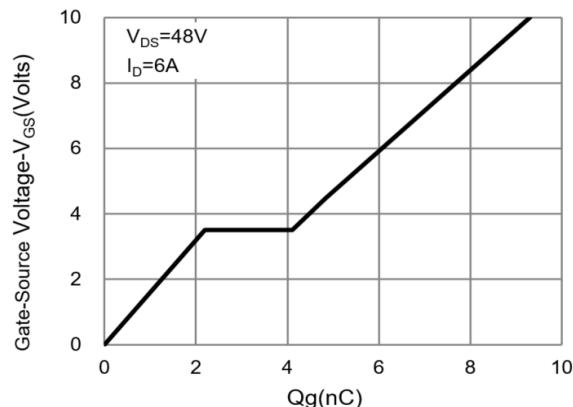


Fig.7 Gate-Charge Characteristics

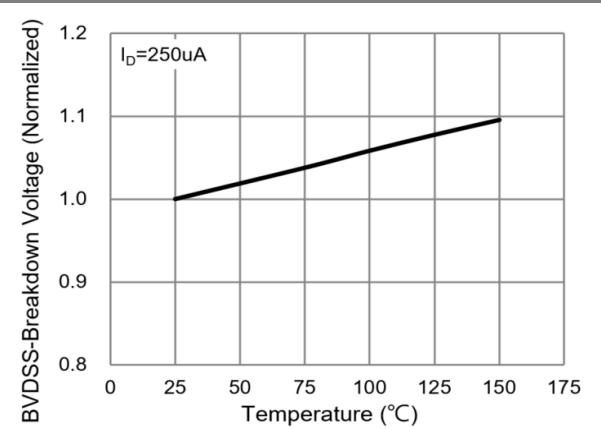


Fig.8 Breakdown Voltage Variation vs. Temperature

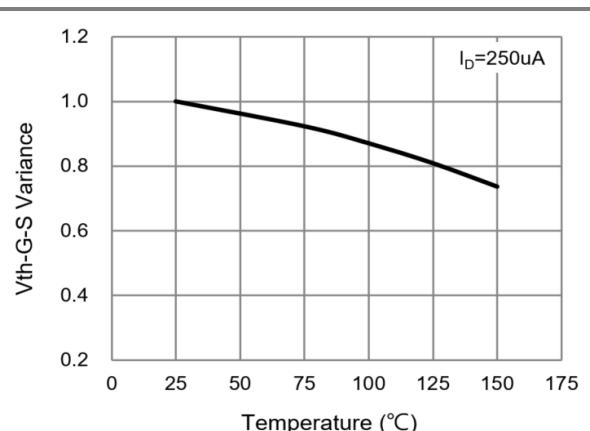


Fig.9 Threshold Voltage Variation with Temperature

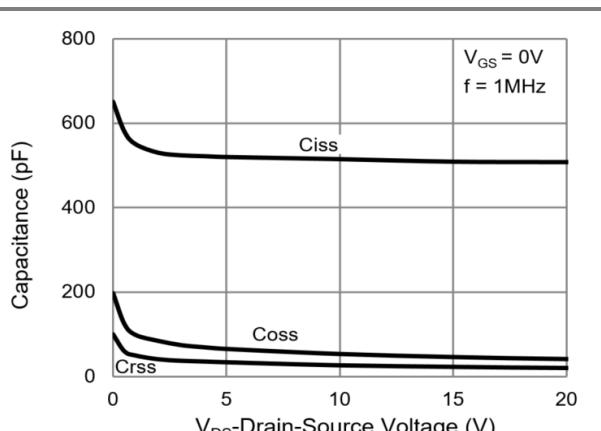


Fig.10 Capacitance vs. Drain-Source Voltage

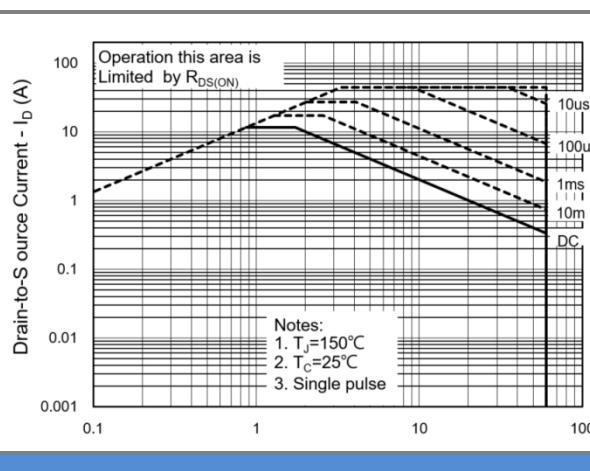


Fig.11 Maximum Safe Operating Area

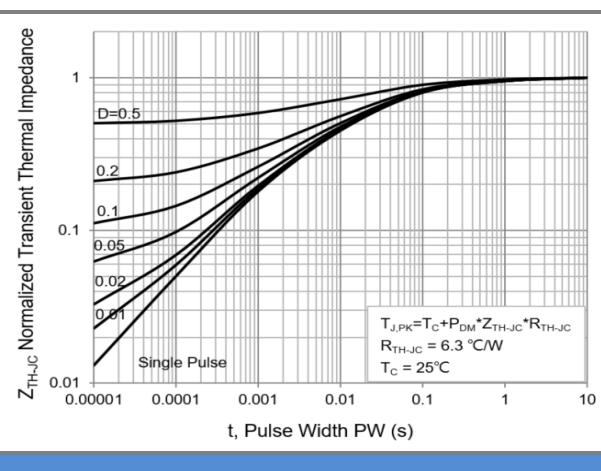


Fig.12 Normalized Transient Thermal Impedance

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## Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking	Version
PJQ4460AP_R2_00001	DFN3333-8L	5K pcs / 13" reel	4460	Halogen free RoHS compliant

## Packaging Information & Mounting Pad Layout

